

60V N-Ch Power MOSFET

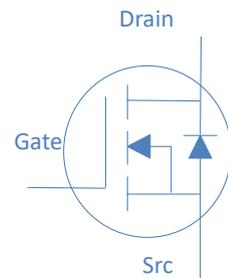
Feature

- ◇ Optimized for high speed switching
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

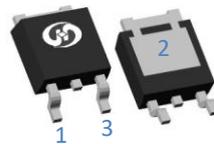
Application

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ Power Tools
- ◇ UPS
- ◇ Motor Control

| | | | |
|-------------------------|---------------|----|------------|
| V_{DS} | | 60 | V |
| $R_{DS(on),typ}$ | $V_{GS}=10V$ | 30 | m Ω |
| $R_{DS(on),typ}$ | $V_{GS}=4.5V$ | 33 | m Ω |
| I_D (Silicon Limited) | | 16 | A |



TO-252



| Part Number | Package | Marking |
|-------------|---------|-----------|
| HTD480N06P | TO-252 | TD480N06P |

Absolute Maximum Ratings at $T_i=25^{\circ}C$ (unless otherwise specified)

| Parameter | Symbol | Conditions | Value | Unit |
|--|----------------|----------------------------|------------|-------------|
| Continuous Drain Current (Silicon Limited) | I_D | $T_C=25^{\circ}C$ | 16 | A |
| | | $T_C=100^{\circ}C$ | 10 | |
| Drain to Source Voltage | V_{DS} | - | 60 | V |
| Gate to Source Voltage | V_{GS} | - | ± 20 | V |
| Pulsed Drain Current | I_{DM} | - | 30 | A |
| Avalanche Energy, Single Pulse | E_{AS} | $L=0.1mH, T_C=25^{\circ}C$ | 12.80 | mJ |
| Power Dissipation | P_D | $T_C=25^{\circ}C$ | 20 | W |
| Operating and Storage Temperature | T_J, T_{stg} | - | -55 to 150 | $^{\circ}C$ |

Absolute Maximum Ratings

| Parameter | Symbol | Max | Unit |
|-------------------------------------|-----------------|------|---------------|
| Thermal Resistance Junction-Case | $R_{\theta JC}$ | 6.25 | $^{\circ}C/W$ |
| Thermal Resistance Junction-Ambient | $R_{\theta JA}$ | 110 | $^{\circ}C/W$ |

Electrical Characteristics at $T_j=25^{\circ}\text{C}$ (unless otherwise specified)
Static Characteristics

| Parameter | Symbol | Conditions | Value | | | Unit |
|-----------------------------------|---------------|---|-------|------|-----------|-----------|
| | | | min | typ | max | |
| Drain to Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=250\mu A$ | 60 | - | - | V |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{GS}=V_{DS}, I_D=250\mu A$ | 0.8 | 1.35 | 2 | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{GS}=0V, V_{DS}=48V, T_j=25^{\circ}\text{C}$ | - | - | 1 | μA |
| Gate to Source Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| Drain to Source on Resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=10A$ | - | 30 | 50 | $m\Omega$ |
| | | $V_{GS}=4.5V, I_D=8A$ | - | 33 | 55 | $m\Omega$ |
| Transconductance | g_{fs} | $V_{DS}=5V, I_D=10A$ | - | 10 | - | S |
| Gate Resistance | R_G | $V_{GS}=0V, V_{DS}$ Open, $f=1\text{MHz}$ | - | 3.40 | - | Ω |

Dynamic Characteristics

| | | | | | | |
|-------------------------------|--------------|--|---|------|---|----|
| Input Capacitance | C_{iss} | $V_{GS}=0V, V_{DS}=20V, f=1\text{MHz}$ | - | 776 | - | pF |
| Output Capacitance | C_{oss} | | - | 51 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 44 | - | |
| Total Gate Charge (10V) | $Q_g (10V)$ | $V_{DD}=20V, I_D=10A, V_{GS}=10V$ | - | 17.5 | - | nC |
| Gate to Source Charge | Q_{gs} | | - | 2.6 | - | |
| Gate to Drain (Miller) Charge | Q_{gd} | | - | 3.6 | - | |
| Turn on Delay Time | $t_{d(on)}$ | $V_{DD}=20V, I_D=1A, V_{GS}=10V, R_G=6\Omega,$ | - | 7.6 | - | ns |
| Rise time | t_r | | - | 16.2 | - | |
| Turn off Delay Time | $t_{d(off)}$ | | - | 40.6 | - | |
| Fall Time | t_f | | - | 7.0 | - | |

Reverse Diode Characteristics

| | | | | | | |
|-------------------------|----------|------------------------------|---|------|-----|----|
| Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_F=15A$ | - | 0.87 | 1.3 | V |
| Reverse Recovery Time | t_{rr} | $I_F=5A, dI_F/dt=100A/\mu s$ | - | 12.1 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | - | 8.8 | - | nC |

Fig 1. Typical Output Characteristics

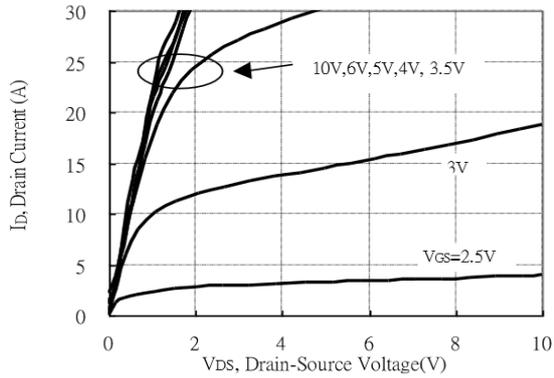


Figure 2. On-Resistance vs. Gate-Source Voltage

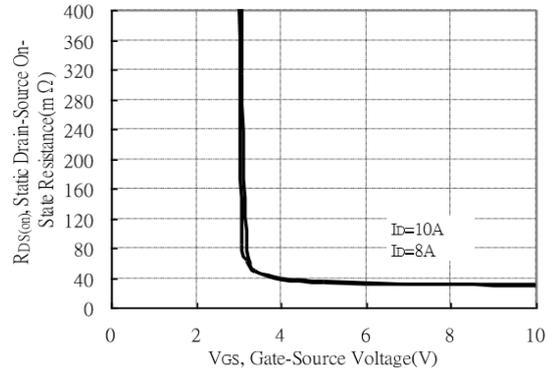


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

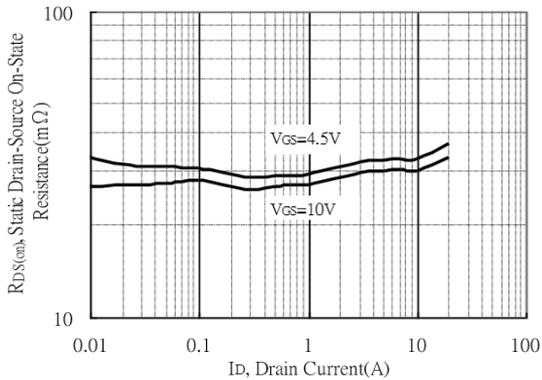


Figure 4. Normalized On-Resistance vs. Junction Temperature

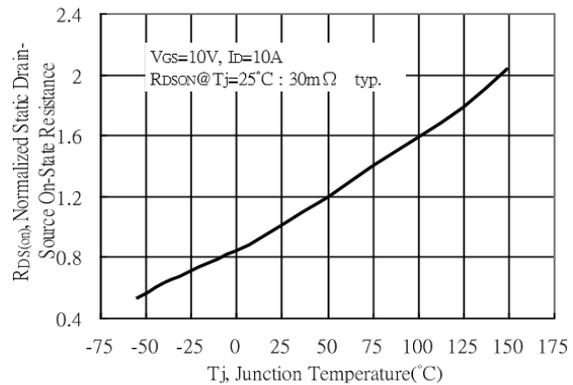


Figure 5. Normalized Threshold Voltage vs. Junction Temperature

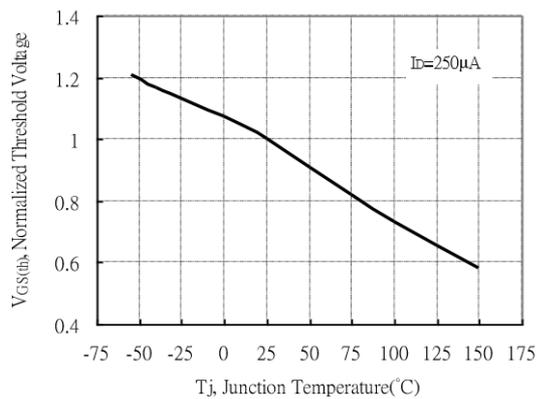


Figure 6. Typical Source-Drain Diode Forward Voltage

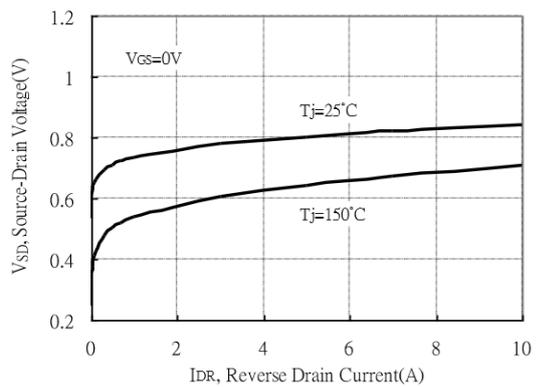


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

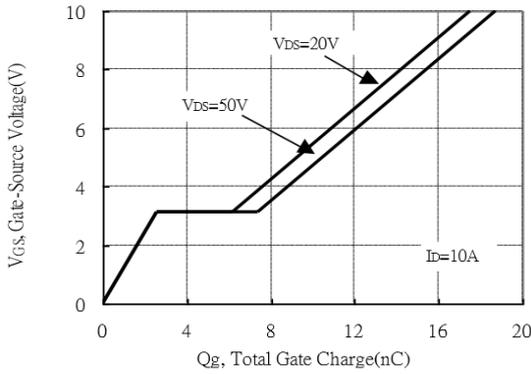


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

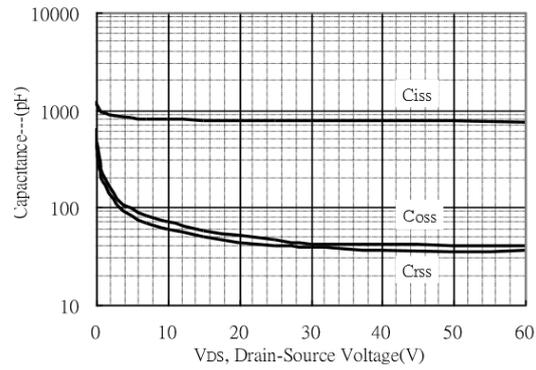


Figure 9. Maximum Safe Operating Area

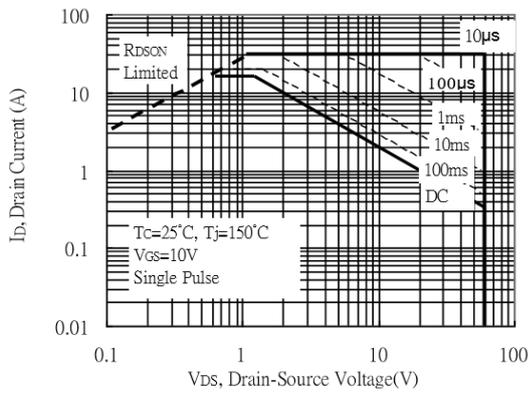


Figure 10. Maximum Drain Current vs. Case Temperature

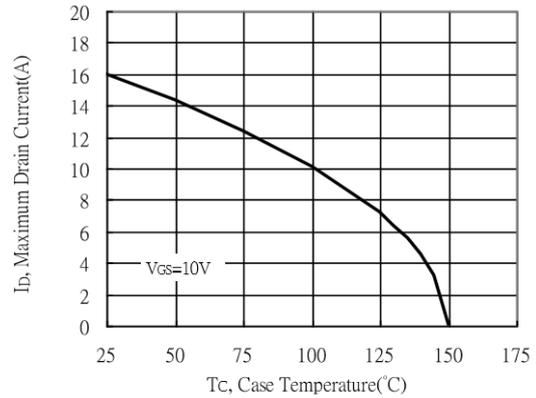
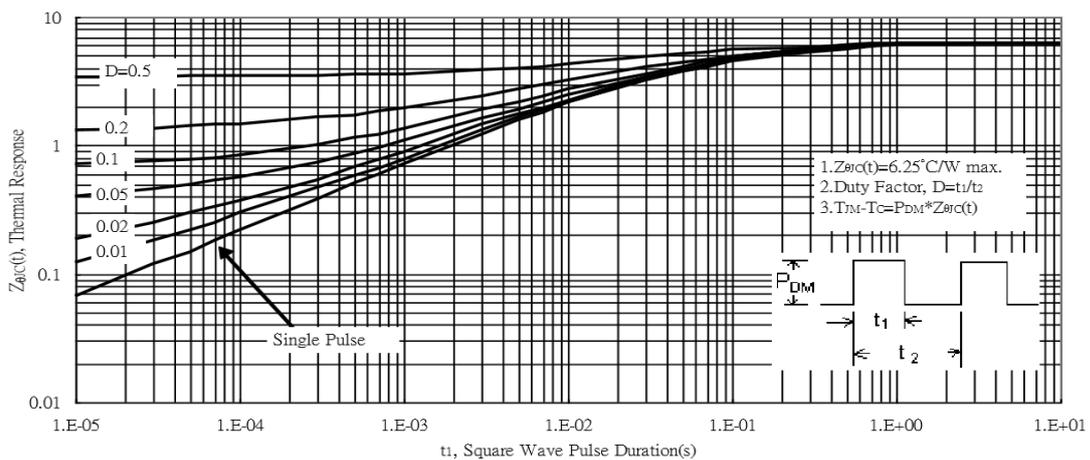
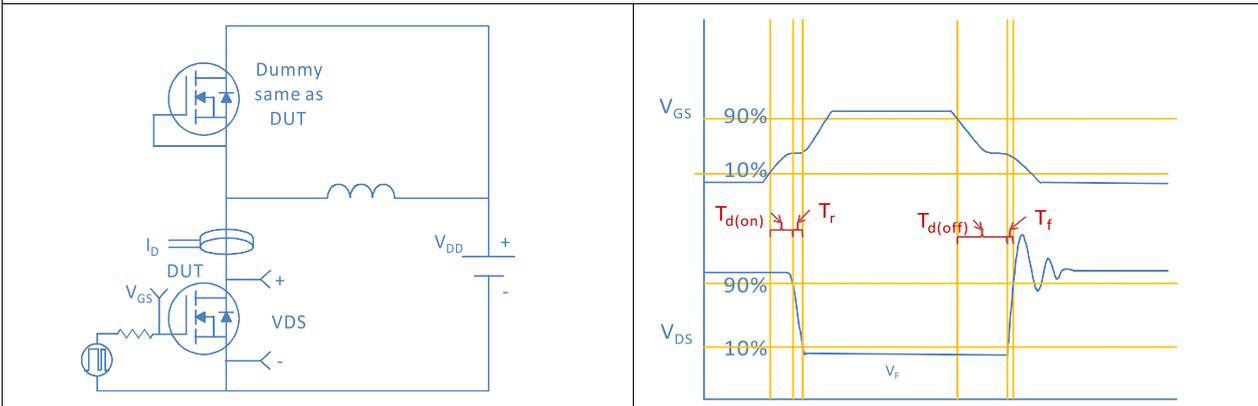


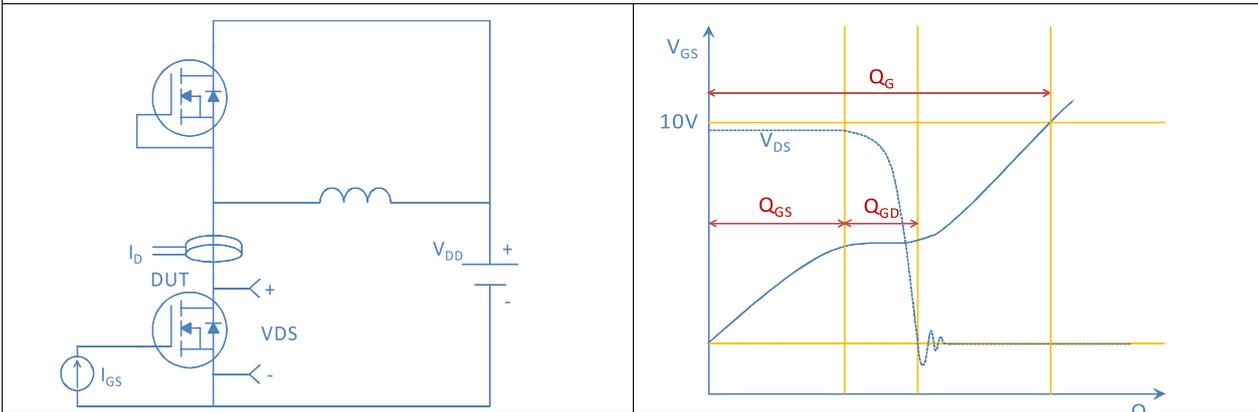
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case



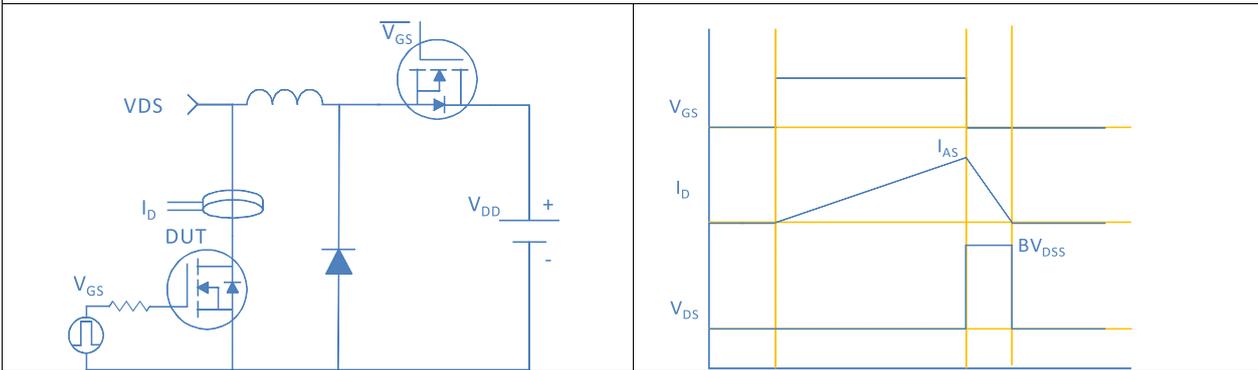
Inductive switching Test



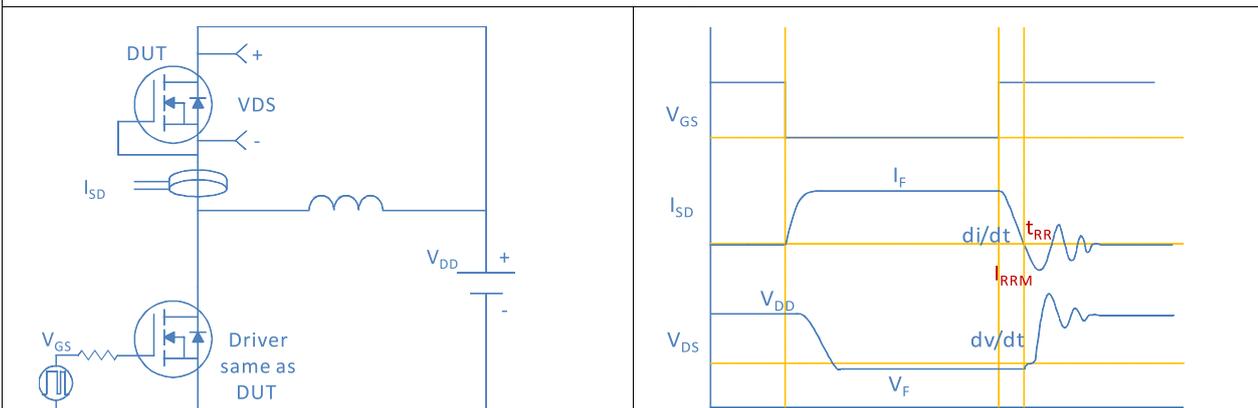
Gate Charge Test

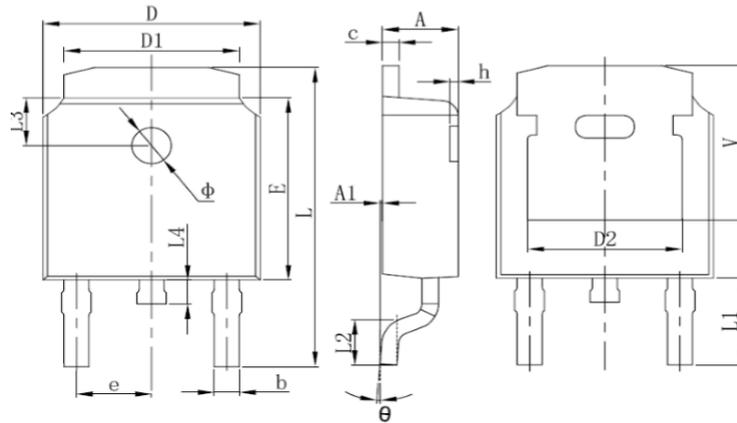


Uclamped Inductive Switching (UIS) Test



Diode Recovery Test



Package Outline
TO-252, 2 Leads


| DIM | Inches | | Millimeters | | DIM | Inches | | Millimeters | |
|-----|--------|-------|-------------|-------|-----|--------|-------|-------------|--------|
| | Min. | Max. | Min. | Max. | | Min. | Max. | Min. | Max. |
| A | 0.087 | 0.094 | 2.200 | 2.400 | L | 0.382 | 0.406 | 9.712 | 10.312 |
| A1 | 0.000 | 0.005 | 0.000 | 0.127 | L1 | 0.114 | REF | 2.900 | REF |
| b | 0.025 | 0.030 | 0.635 | 0.770 | L2 | 0.055 | 0.067 | 1.400 | 1.700 |
| c | 0.018 | 0.023 | 0.460 | 0.580 | L3 | 0.063 | REF | 1.600 | REF |
| D | 0.256 | 0.264 | 6.500 | 6.700 | L4 | 0.024 | 0.039 | 0.600 | 1.000 |
| D1 | 0.201 | 0.215 | 5.100 | 5.460 | Φ | 0.043 | 0.051 | 1.100 | 1.300 |
| D2 | 0.190 | REF | 4.830 | REF | θ | 0° | 8° | 0° | 8° |
| E | 0.236 | 0.244 | 6.000 | 6.200 | h | 0.000 | 0.012 | 0.000 | 0.300 |
| e | 0.086 | 0.094 | 2.186 | 2.386 | v | 0.207 | REF | 5.250 | REF |